



mmW Solutions. Enabling a new world

All-Silicon Active Antennas for High Performance and low-cost mmWave Systems

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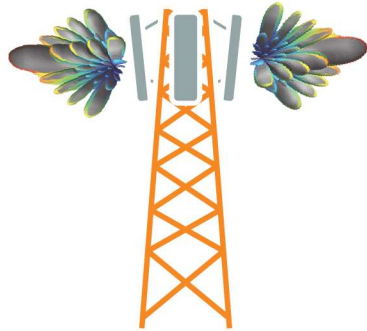
Anokiwave, Inc.
Billerica, MA, USA



mmW Solutions. Enabling a new world



Several major markets for mmWave systems



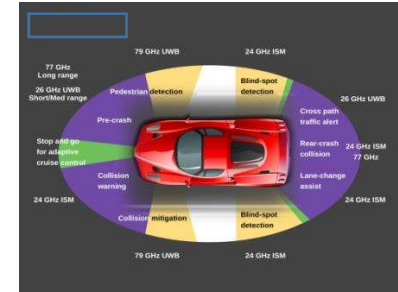
5G

- High power gNodeB
- Fixed wireless access
- Backhaul, Fronthaul, Repeater
- Small cell access point
- Indoor/outdoor CPE
- Mobile devices



SATCOM

- Ku Band terminal
- Ka Band terminal
- Airborne arrays
- Marine terminal
- Remote area internet access



RADAR

- Collision avoidance, detection
- Pedestrian detection
- Obstacle detection
- 24GHz, 77GHz

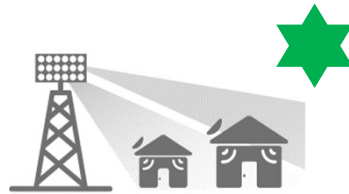
Blossom of 5G Uses Cases demands a Scalable Architecture

Anokiwave well positioned with 3 Generation of mmW IC's

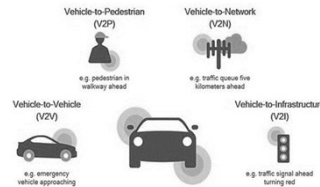
High Power Base Stations



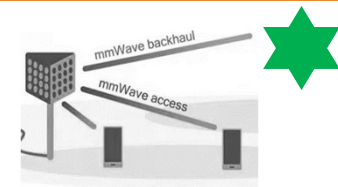
Fixed Wireless Access



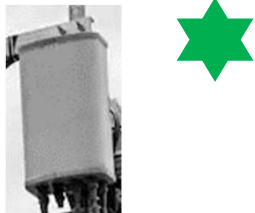
Embedded Vehicle, V2X



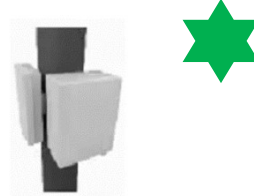
mmWave Integrated Access & Backhaul



Medium Power Microcells



Outdoor CPE, Repeater



Access Points, Indoor CPE



Embedded Laptop



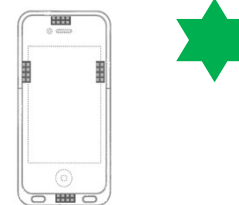
Embedded Tablet



Hotspot Device



Mobile Phone

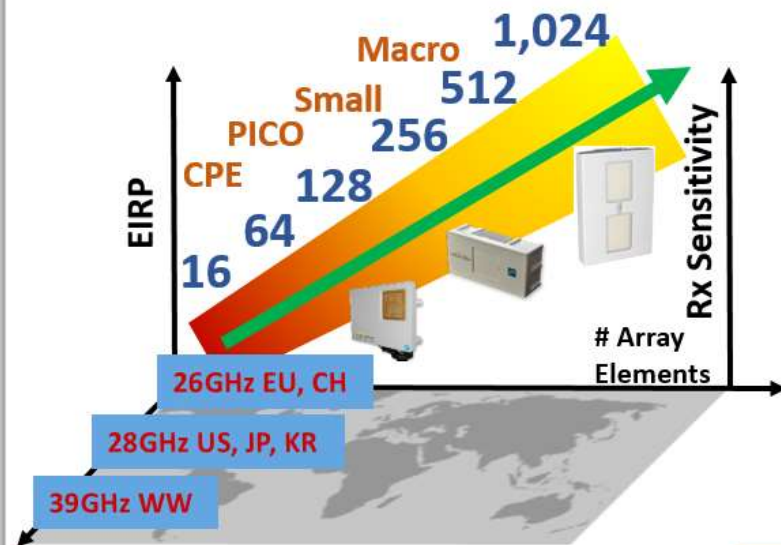


M2M IoT Device



*US is moving ahead with mmWave, 24GHz Spectrum auction is ongoing

Si BFIC to cover ALL popular 5G mmW Bands



Anokiwave covers all 5G bands

1

2016

World's first 28GHz, 39GHz silicon quad IC for 5G markets

2

2018

24/26, 28, 39GHz quad ICs with more linear power, lower cost silicon

3

2019

24/28/39 ICs supporting 8Tx, 8Rx channels

IFIC paired with BFIC

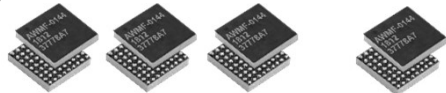
4

2020

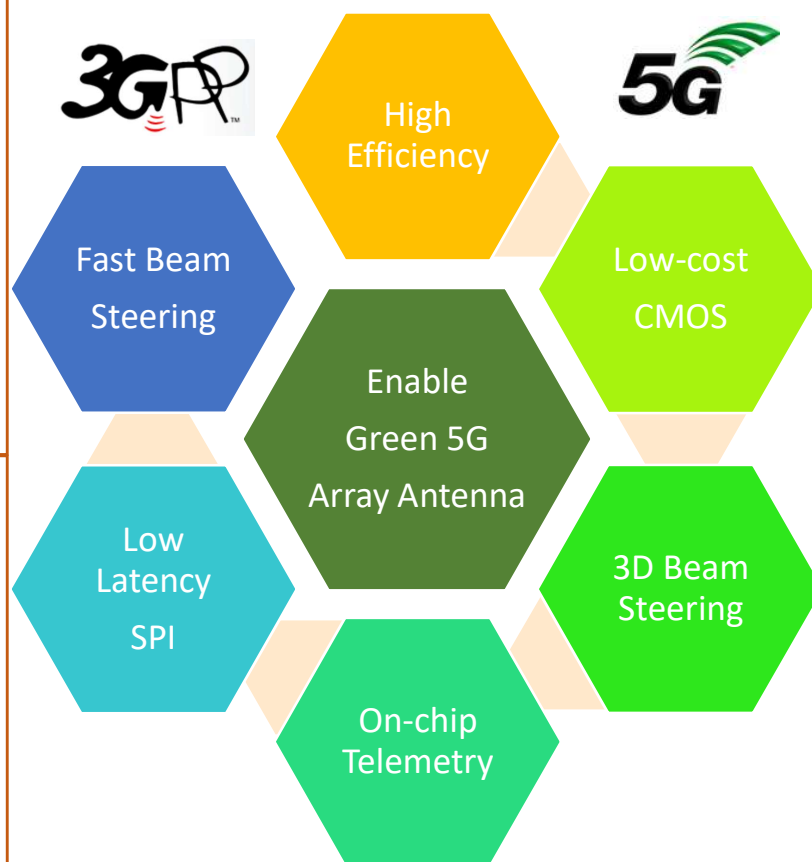
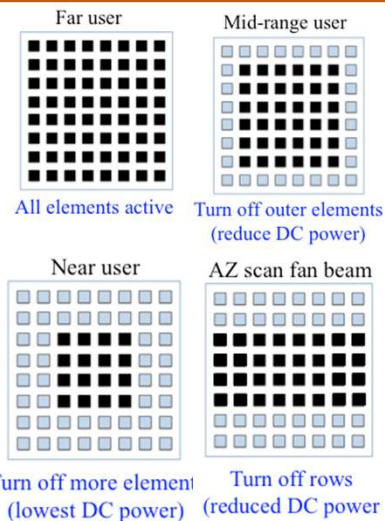
Features being defined

Rich features, functions, easy implementation and lowest cost

24/26GHz 28GHz 39GHz New Band

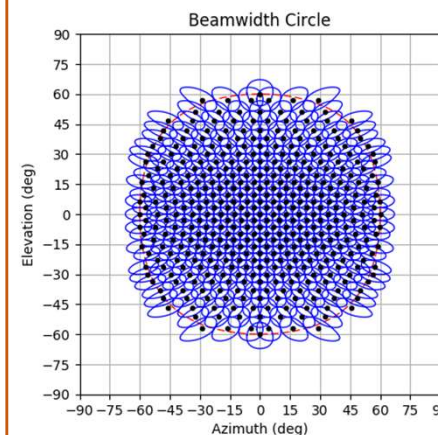
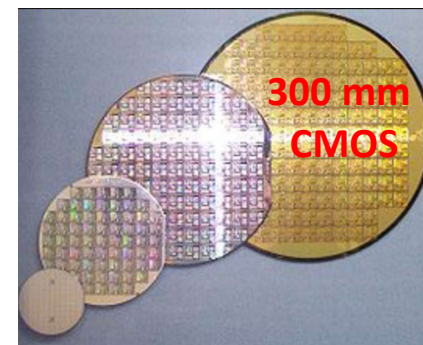


Same SPI Interface
Same PIN out
Same IC Size
One SW Control Package



Broadest BFIC Portfolio

The larger Wafer, the lower Cost



Two critical factors for commercializing 5G mmWave

TECHNICAL FACTORS

- Link budget (EIRP, EIS, ...)
- Power dissipation
- System size* and weight
- 3GPP Standards

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- High $\frac{EIRP (W)}{Pdiss (W)}$ ratio
- Low ACLR, EVM
- Low noise figure
- Transient performance
- On-chip telemetry



**All-Silicon mmWave
antennas address
both factors well**

ECONOMIC FACTORS

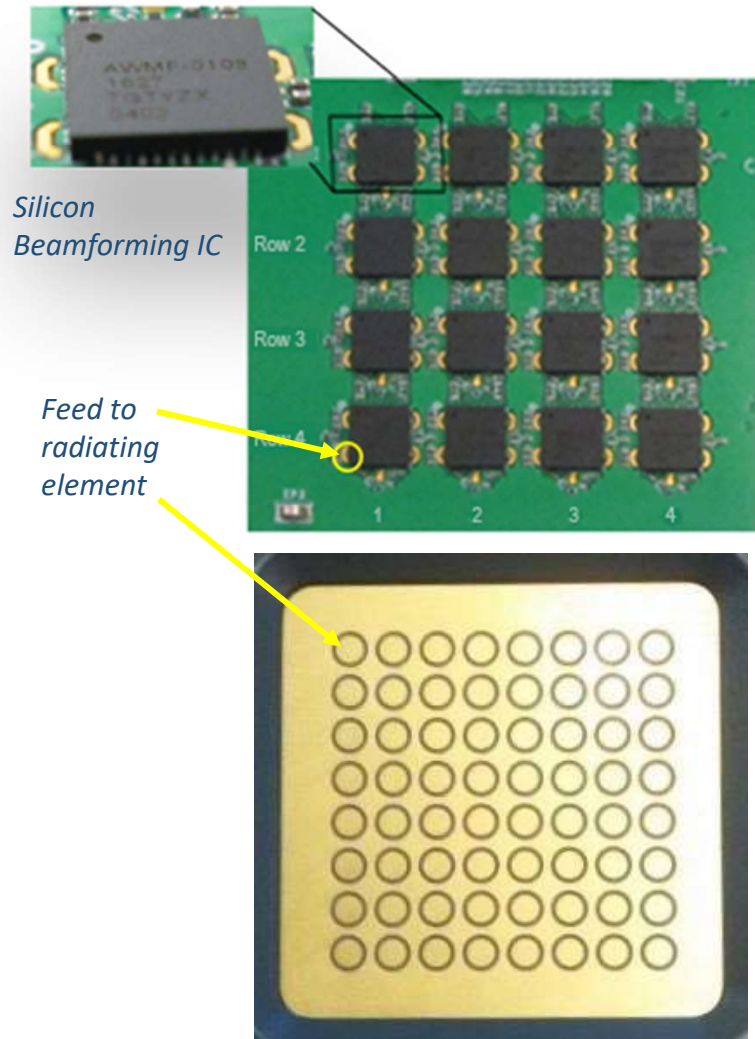
- System development cost
- Operator's Capex
- Ongoing Opex
- Supply chain diversity

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- Planar arrays
- Low cost silicon wafers
- Low prime power
- Minimal array calibration
- Remote monitoring
- Eco-system of array manufacturers

*Size is key issue for Regulatory Approval at local Government level

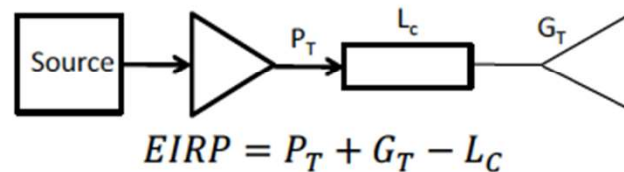
All-Silicon Array Architecture



- Low cost, high volume Si wafer fabrication
- Wideband high linearity and low noise RF performance
- Single positive supply operation
- Highly integrated, small size RFIC
- Multiple RF channels per IC – 4X, 8X BFIC
- IC size enables 2D beam steering in AZ and EL
- Lowest feed loss gives optimum Tx power efficiency and Rx NF
- Combines analog and digital circuits (SoC)

EIRP vs. Conducted Power

The FCC defines EIRP as the sum of three logarithmic terms:



- * Path loss after signal amplification (TR switch + Transmission Line + Antenna Feed) wastes power *at the most valuable point in the system*
 - * Excess power dissipated in the interconnect loss is converted to thermal energy (bad) and requires a larger (more expensive) PSU than required
- Power dissipation/optimization is a holistic assessment of the entire path/system
 - Active antenna efficiency/functionality needs to consider all elements in the signal path AND control path of the sub-array for an apples-apples comparison
 - Non-signal path functions include embedded controllers and the PSU
 - This function is normalized to the sub-array level to account for beam-forming architecture (hybrid/analog/digital)

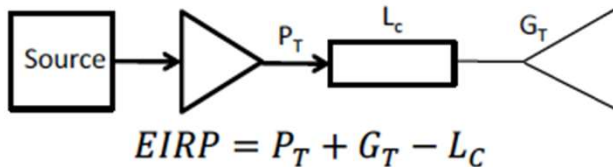
EIRP should be maximized by controlling all three contributing terms:

- Maximizing conducted linear power for lowest power dissipation
- Increasing the available array gain to the maximum allowed by the application
- Minimizing the effect of system losses (which can be dramatic at mmWave)

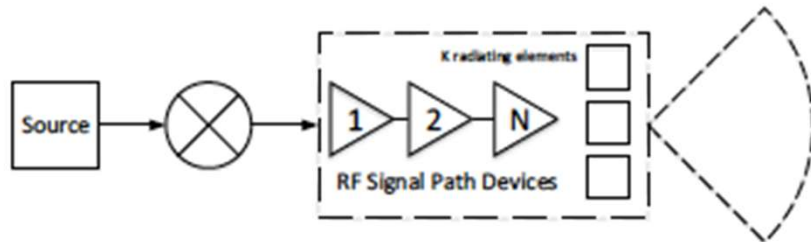
Thermally Limited System Integration

**EIRP must be generated
*even more efficiently***

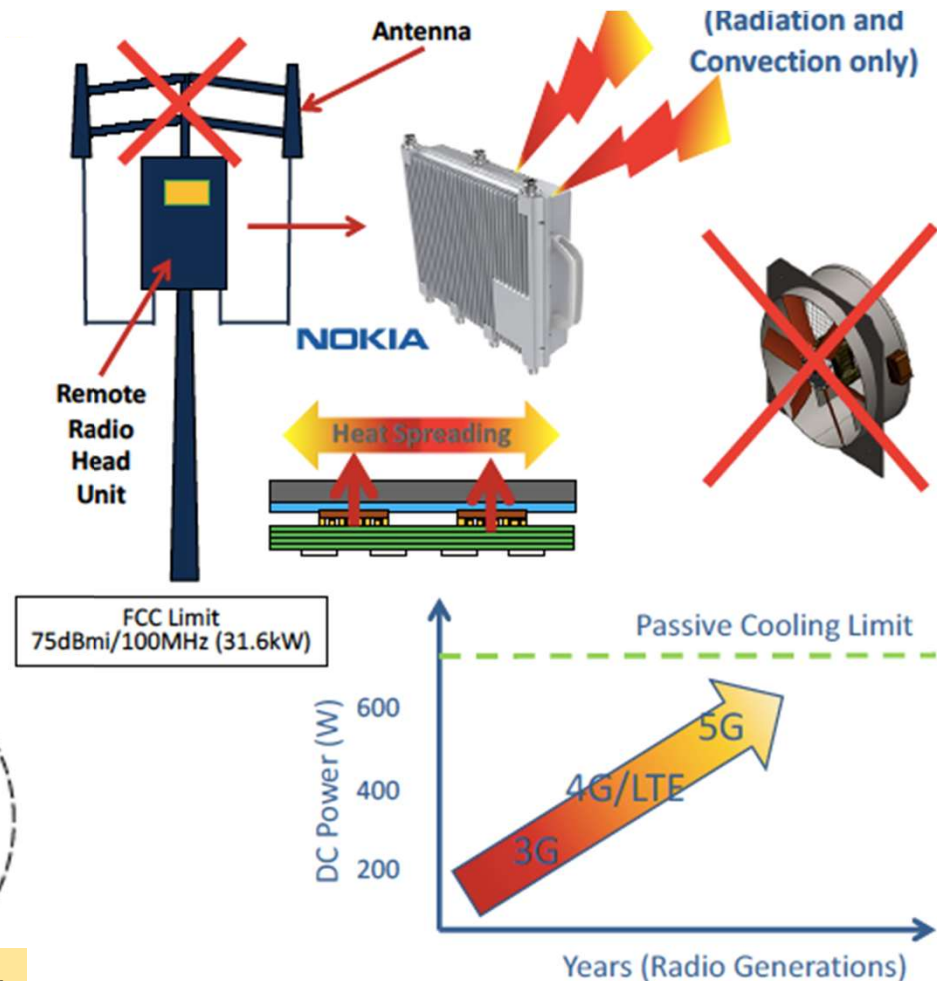
- Passive antenna replaced by AESA
- Fans and active cooling precluded by reliability concerns



Path loss after signal amplification (TR switch + Transmission line + Antenna feed) wastes power at **the most valuable point in the system**



Key FoM is overall Transmitter Efficiency



Generating efficient, linear TX power at wide channel bandwidths is a critical challenge

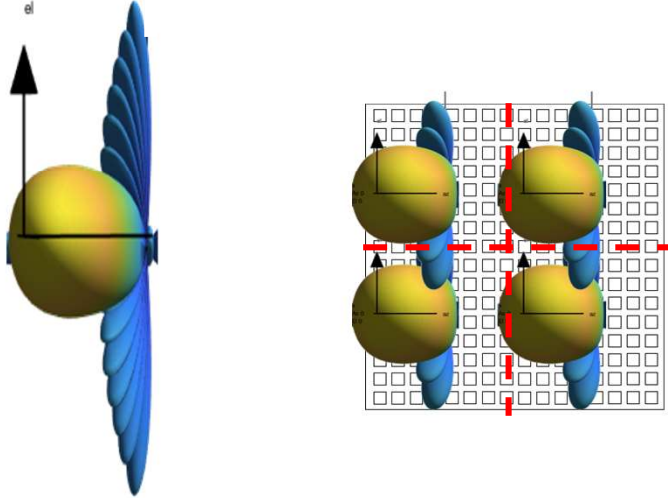
- $\text{EIRP} \propto (\text{No. Elements})^2$
- Power dissipation $\propto (\text{No. Elements})$
 \therefore Larger arrays are better
 Cost and narrow beamwidth limit the size
- Efficiency is set by the **waveform**, independent of device technology (GaAs, GaN, SiGe, CMOS)
- 3% or -30dB EVM using 5G NR 400MHz waveform is a common requirement for OFDM 64QAM waveform
- Linear power is more important than P1dB

Evolution of Modern Communication Systems

	Standard	Bandwidth MHz	EVM dB	Waveform Modulation
WiFi	802.11b	20	-9	DQPSK
	802.11g/a	40	-25	OFDM
	802.11ac wave 1	80	-30	OFDM 256QAM
	802.11ac wave 2	160	-32	OFDM 256QAM
	802.11ax	160	-35	OFDM 1024QAM
Cellular	GSM	0.2	-23	GMSK-8PSK
	WCDMA	3.84	-15	QPSK
	LTE	20	-22	OFDM
	LTE-A	40	-27	OFDM
5G	5GTF	800	-30	OFDM 64QAM
	5G-NR	1400	-32	OFDM 256QAM

What level of output power back-off (OBO) is needed to meet the required EVM for low BER?

Reconfigurable 28GHz All-silicon Array



US Trade Compliant Solution (5A991.f)

Enables 4x4 MIMO

Full 2D scan for dense urban environments

- >1KW EIRP at OP1dB in 256-element mode ($\sim 65W P_{DISS}$)
- One 256 element beam or four 64 element beams
- 4x64 arrays for MU-MIMO
- Weather sealed for outside deployment
- Passive thermal management
- 26.4cm x 14.2cm x 6.9cm
- Mass: 3kg
- Embedded controller for simple UI
- Single 12V DC input

Active antenna region



Summary

- mmWave silicon core ICs for active antennas are commercially available now
- All-silicon, high efficiency planar arrays are in production today
 - 5G, SATCOM, Automotive Radar markets
- The momentum for increased industrialization is growing quickly
- We are beyond proof-of-concept and academic research
- Silicon provides a clear path to high volume manufacturing and the industrialization required to mass produce efficient, cost effective arrays



Thank You

